



L I G H T W A V E L O G I C®

Investor Presentation

January 2026

Forward Looking Statements

This slide presentation contains “forward-looking statements” and “forward-looking information” within the meaning of the Private Securities Litigation Reform Act of 1995. This information and these statements, which can be identified by the fact that they do not relate strictly to historical or current facts, are made as of the date of this presentation or as of the date of the effective date of information described in this presentation, as applicable. The forward-looking statements herein relate to predictions, expectations, beliefs, plans, projections, objectives, assumptions or future events or performance (often, but not always, using words or phrases such as “expects”, “anticipates”, “plans”, “projects”, “estimates”, “envisages”, “assumes”, “intends”, “strategy”, “goals”, “objectives” or variations thereof or stating that certain actions, events or results “may”, “can”, “could”, “would”, “might” or “will” be taken, occur or be achieved, or the negative of any of these terms and similar expressions) and include, without limitation, statements with respect to projected financial targets that the company is looking to achieve.

All forward-looking statements are based on current beliefs as well as various assumptions made by, and information currently available to the company’s management team. A more detailed description of the risks presented by those assumptions and other risks are more fully described by the company under the caption “Risk Factors” included in our SEC filings and other risks to which our company is subject, and various other factors beyond the company’s control.

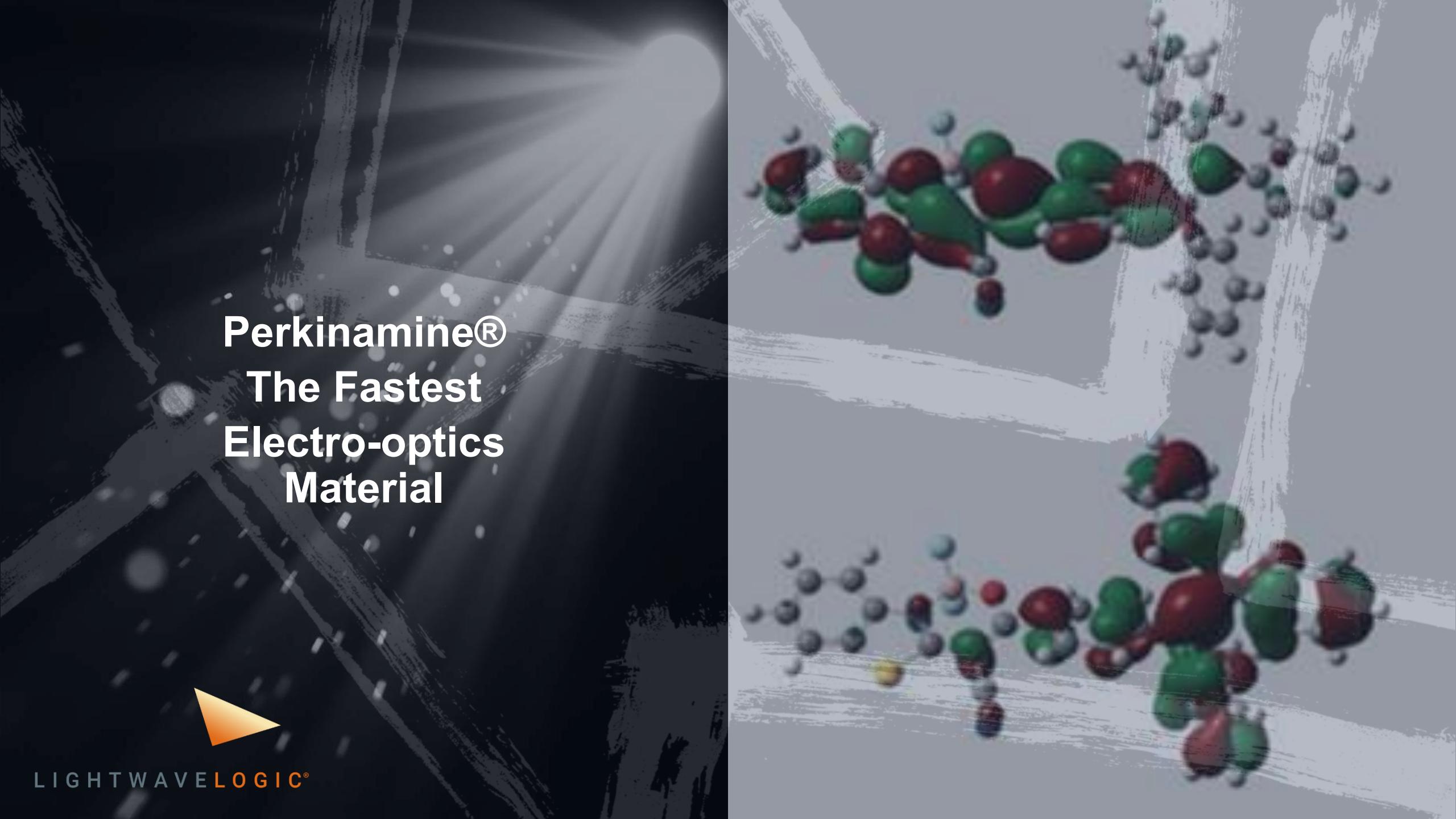
By their very nature, forward-looking statements involve inherent risks and uncertainties, both general and specific, and risks exist that estimates, forecasts, projections and other forward-looking statements will not be achieved or that assumptions do not reflect future experience. We caution any person reviewing this presentation not to place undue reliance on these forward-looking statements as a number of important factors could cause the actual outcomes to differ materially from the beliefs, plans, objectives, expectations, anticipations, estimates assumptions and intentions expressed in such forward-looking statements.

The company does not undertake to update any forward-looking statement, whether written or oral, that may be made from time to time by company or on behalf of the company except as may be required by law.

Imagine a flashlight turning on and off
100 billion times per second



LIGHTWAVE LOGIC®



Perkinamine®
The Fastest
Electro-optics
Material



LIGHTWAVE LOGIC®

Experienced Management Team



Yves LeMaitre
Chief Executive Officer &
President



Dr. Aref Chowdhury
Chief Technology Officer &
Head of Strategy



NOKIA Bell Labs

Alcatel-Lucent 



Dr. Robert Blum
SVP, Sales & Marketing



Dr. Lance Thompson
VP of Engineering



Realigned management team brings broad operational and research expertise across photonics ecosystem

AI Infrastructure Facing New Challenges



LIGHTWAVE LOGIC®



CONNECTIVITY

BANDWIDTH

POWER

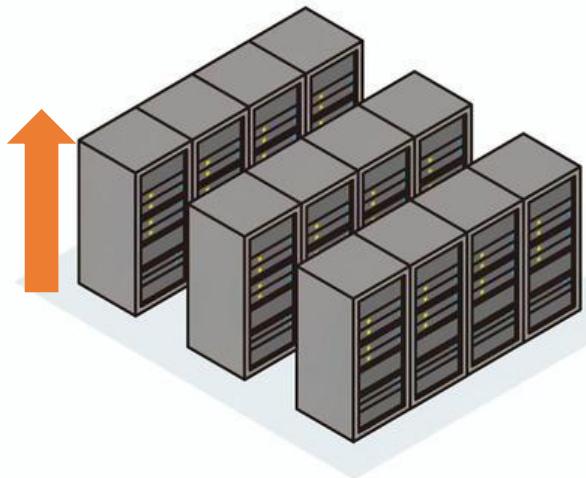
INTEGRATION

AI Cluster Opportunity (Scale X)



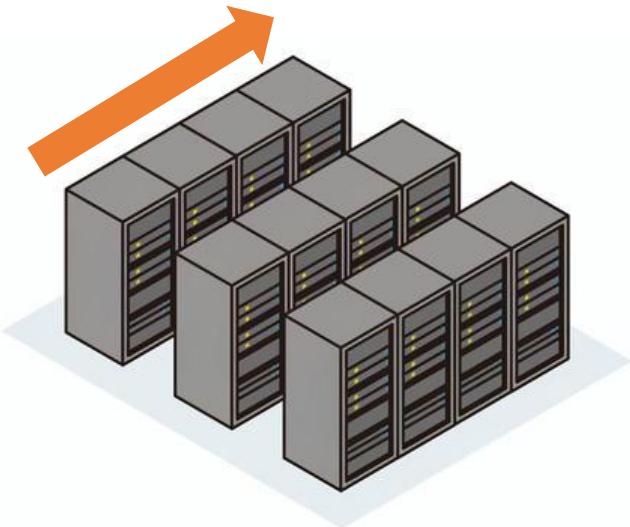
Scale Up

Within the Rack



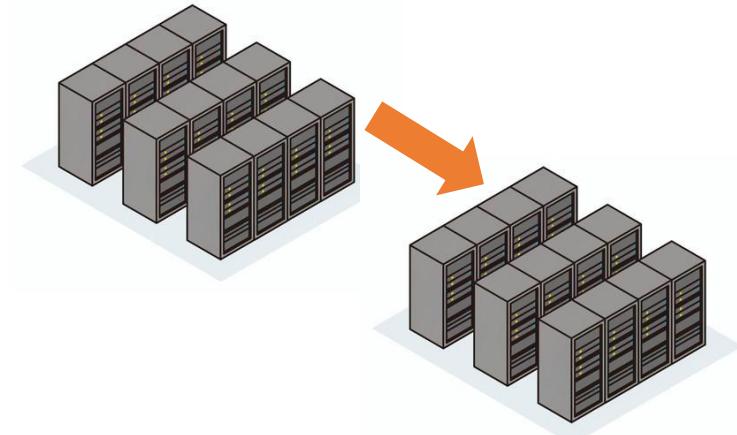
Scale Out

Across Racks



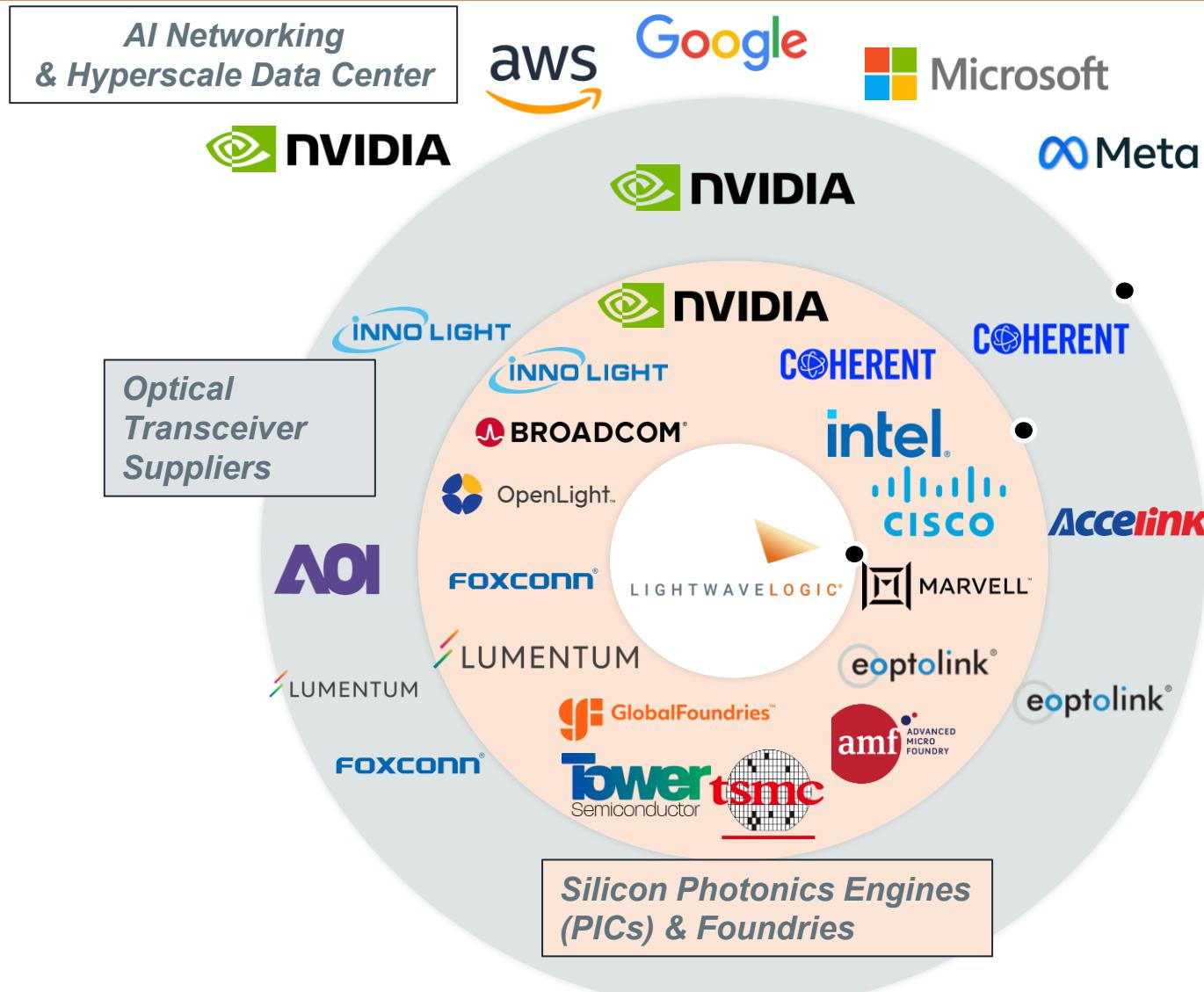
Scale Across

Between Data Centers



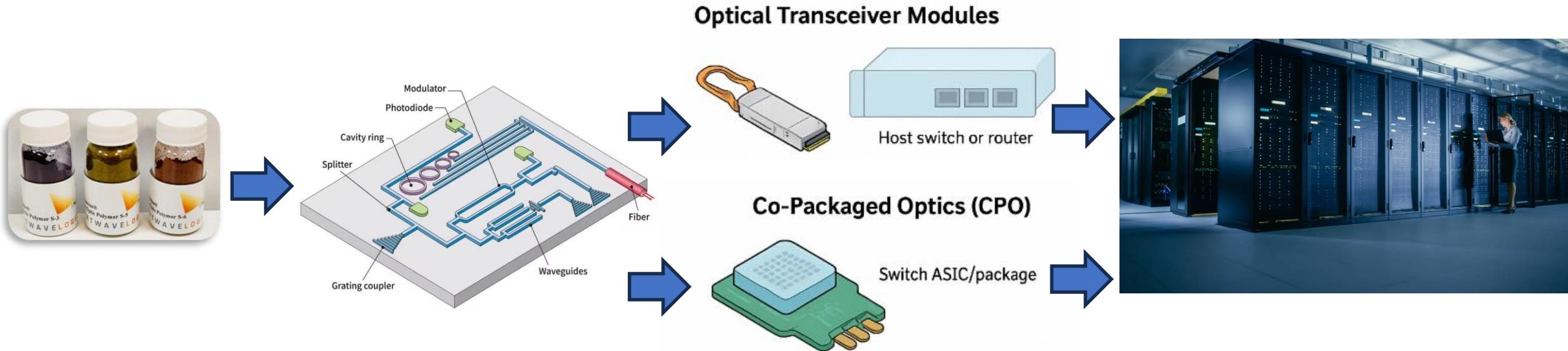
Our polymer technology can address each of these scaling challenges

Enabling AI Connectivity Ecosystem



Note: Companies represent examples of established entities per segment only.

The Product Design Process



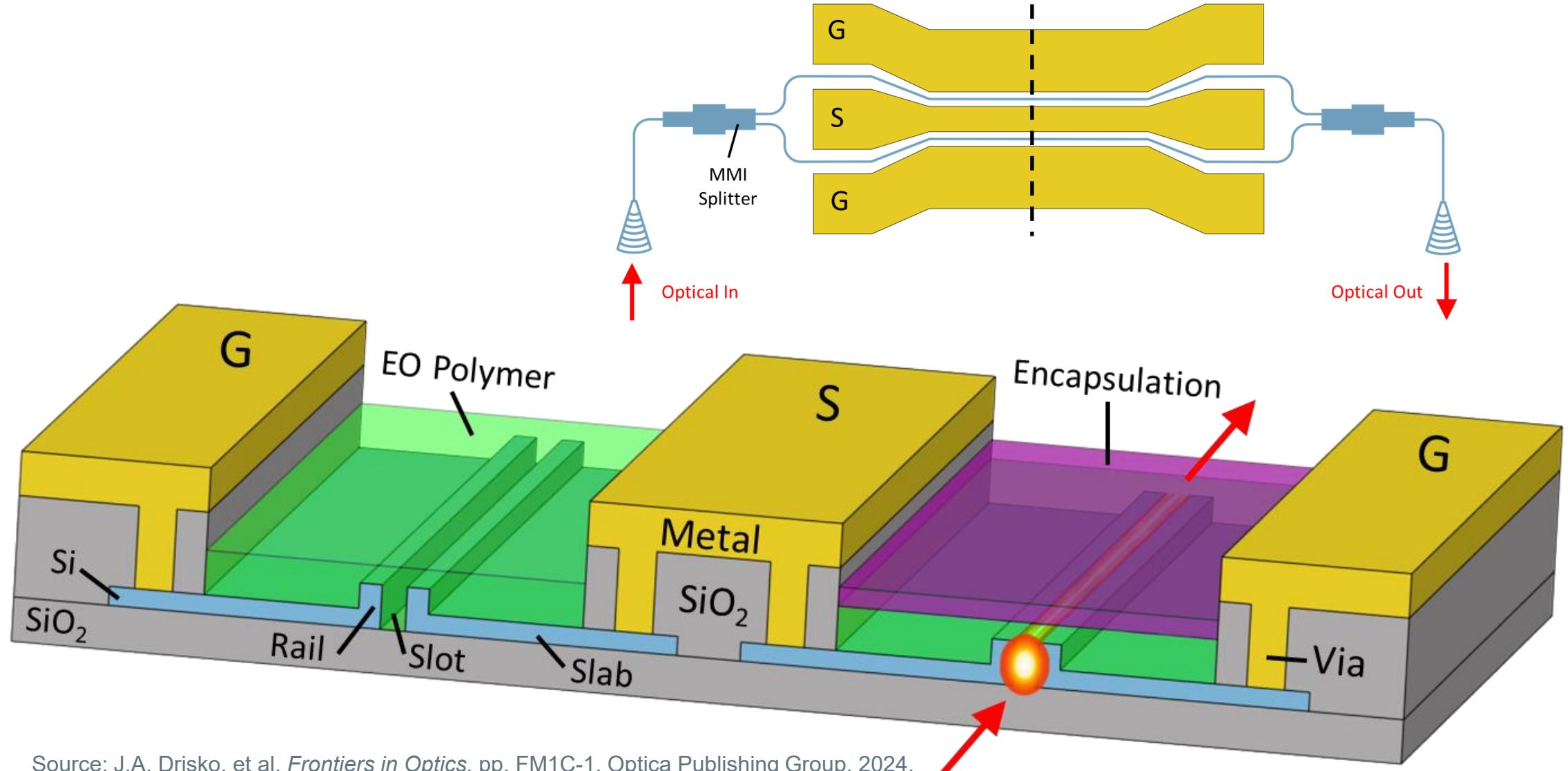
Perkinamine
EO Polymer

Silicon Photonics
PIC (Photonics
Integrated Circuit)

Integrated Optical
Module

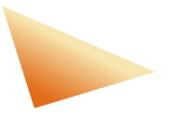
Datacenter or AI Factory

Polymer Slot Modulators

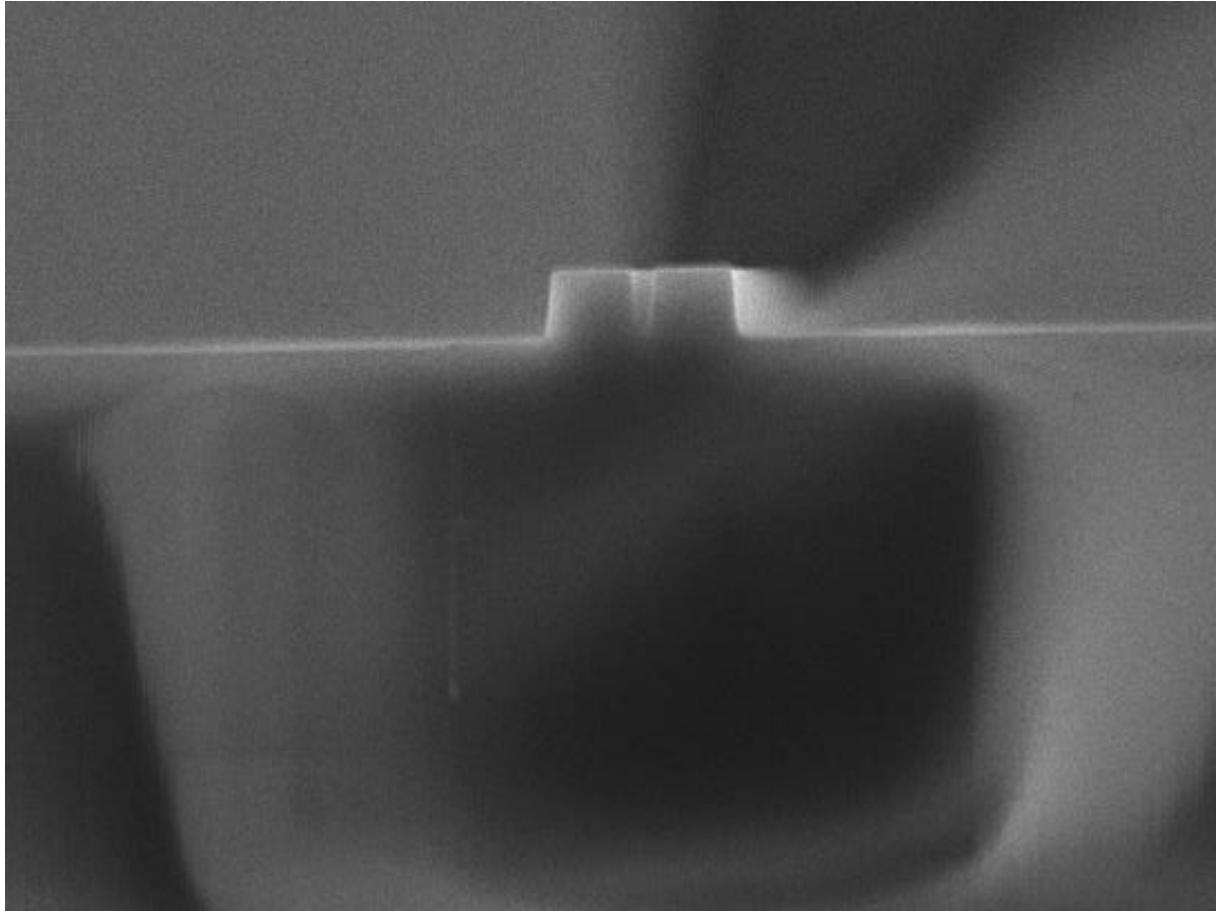


Source: J.A. Drisko, et al. *Frontiers in Optics*, pp. FM1C-1. Optica Publishing Group, 2024.

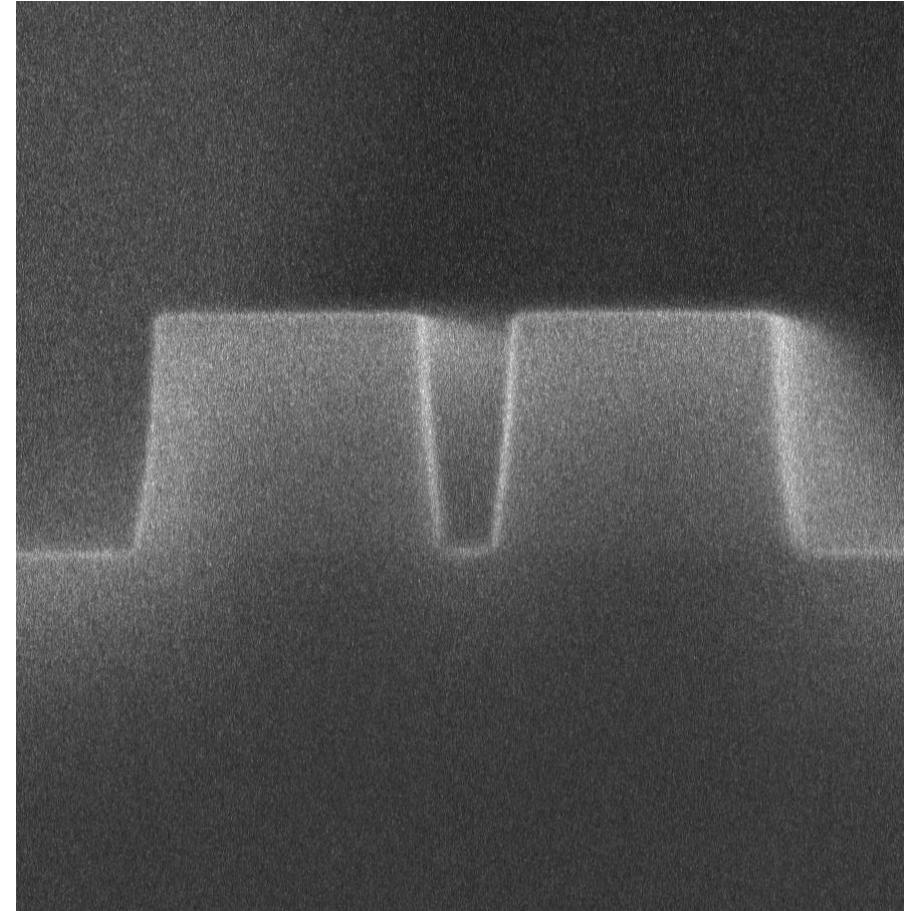
Si Slot Waveguide Cross Sections



LIGHTWAVE LOGIC®



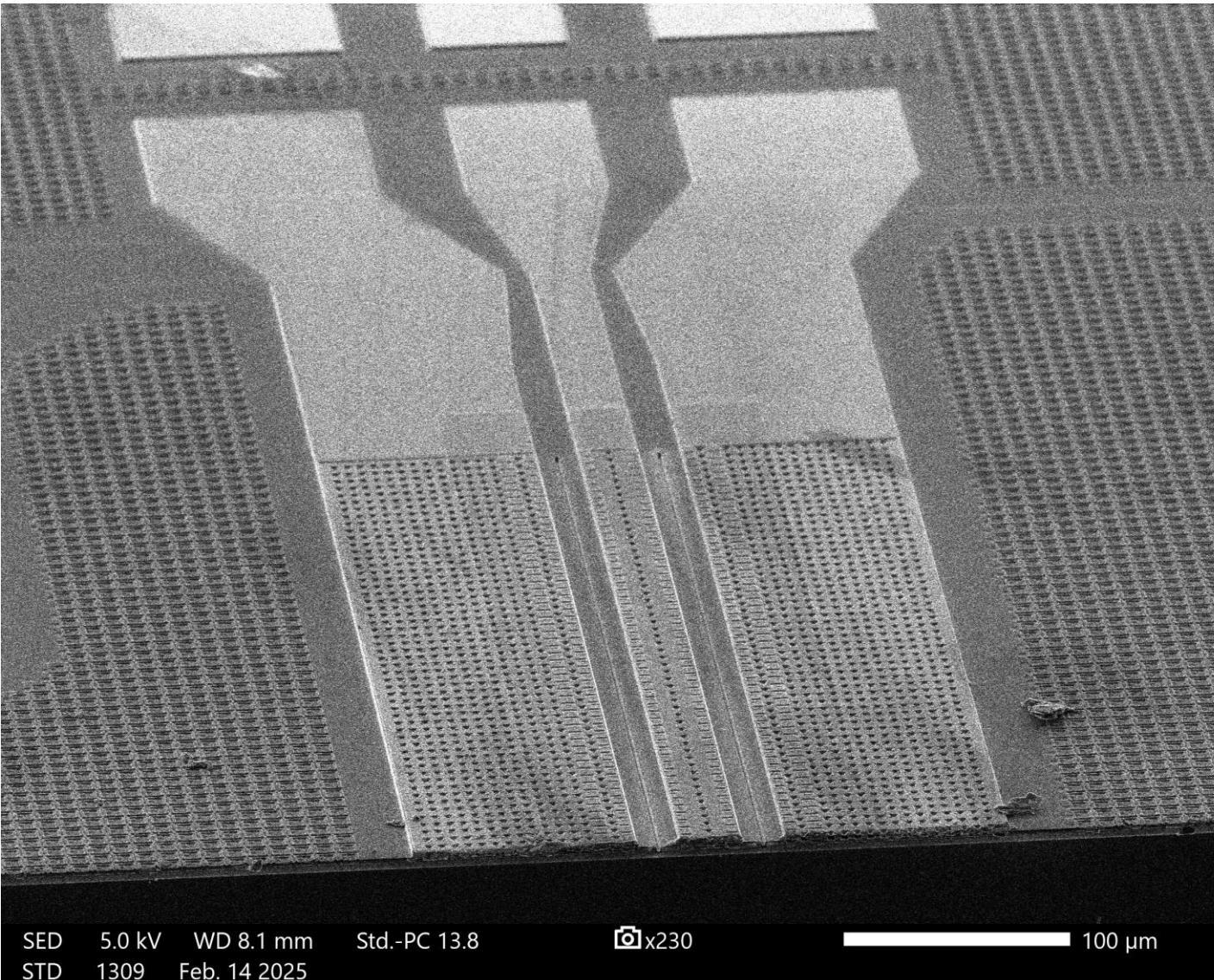
500 nm



100 nm

Clean, sharp, and smooth Si slots

Device after Polymer Integration



Strong Patent Portfolio



LIGHTWAVE LOGIC®

**80+ U.S. and international patents and applications that are issued or pending;
Patent portfolio spans all major aspects of manufacturing and operations**



Materials

- Innovating new EO chromophores and molecular architectures to meet application needs such as high electro-optic activity and stability



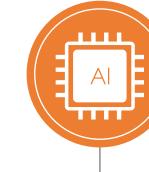
Optical Devices

- Engineering ways to enhance device performance by means of device design and optimized controls as we demonstrate our materials in devices, such as modulators



Fabrication

- Materials innovations are followed by methods in which we or our partners can best work with the materials in the fabrication process



Integration

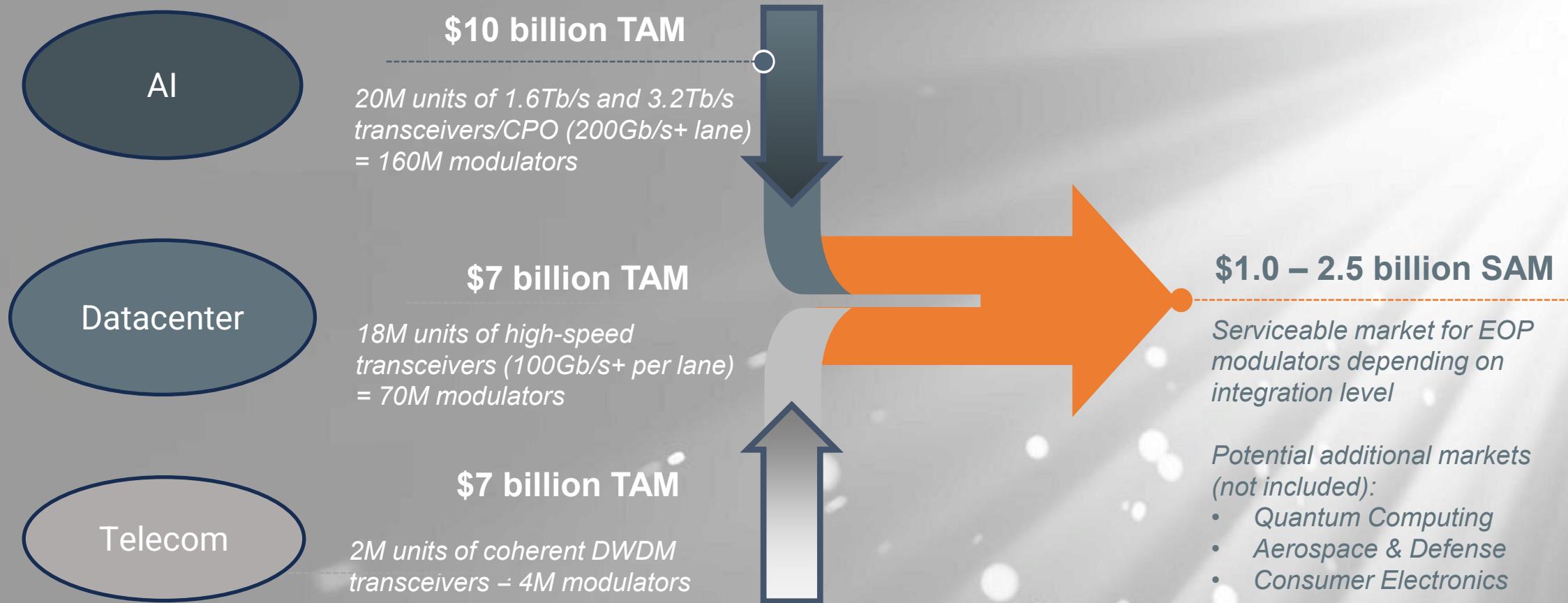
- Polymers can be used to add functionality to existing semiconductor devices to innovate how to get light from one material system into another with minimal losses



Packaging

- Key challenge of maintaining the quality of radio-frequency electrical signals and hermetic sealing of devices for durability (while still allowing light to go through)

2028 Estimated Total Addressable Market (TAM) & Serviceable Addressable Market (SAM)*



* Source: LightCounting, internal company estimates

Electro-optic Polymers in Quantum Applications

Quantum Computing
TAM 2035: \$28B



Quantum Communications
\$11B

Quantum Sensing
\$7B

Lightwave Logic, Inc. and QPICs Announce Partnership to Advance the Use of Electro-Optic Polymers in Quantum Processors

01/15/2026

Companies to jointly develop PDK for PIC-based quantum solutions

ENGLEWOOD, COLORADO / [ACCESS Newswire](#) / January 15, 2026 / Lightwave Logic, Inc. (NASDAQ:LWLG) (the "Company"), a technology platform company leveraging its proprietary electro-optic (EO) polymers to transmit data at higher speeds with less power in a small form factor, and QPICs, a newly established foundry dedicated to advancing Photonic Integrated Circuit (PIC) based quantum technology as part of the Quantum Tech Hub initiative in Colorado, today announced the signing of a memorandum of understanding (MOU) to accelerate the use of electro-optic polymers for the commercialization of photonic quantum circuits.

The MOU will enable QPICs to develop Process Design Kits (PDKs) with Lightwave Logic's proprietary polymer platform and encapsulation processes with the goal of accelerating PIC production timelines for quantum computing customers. The availability of the PDK will allow these customers to design custom solutions based on silicon circuits without the need for extensive modifications of PIC manufacturing processes.

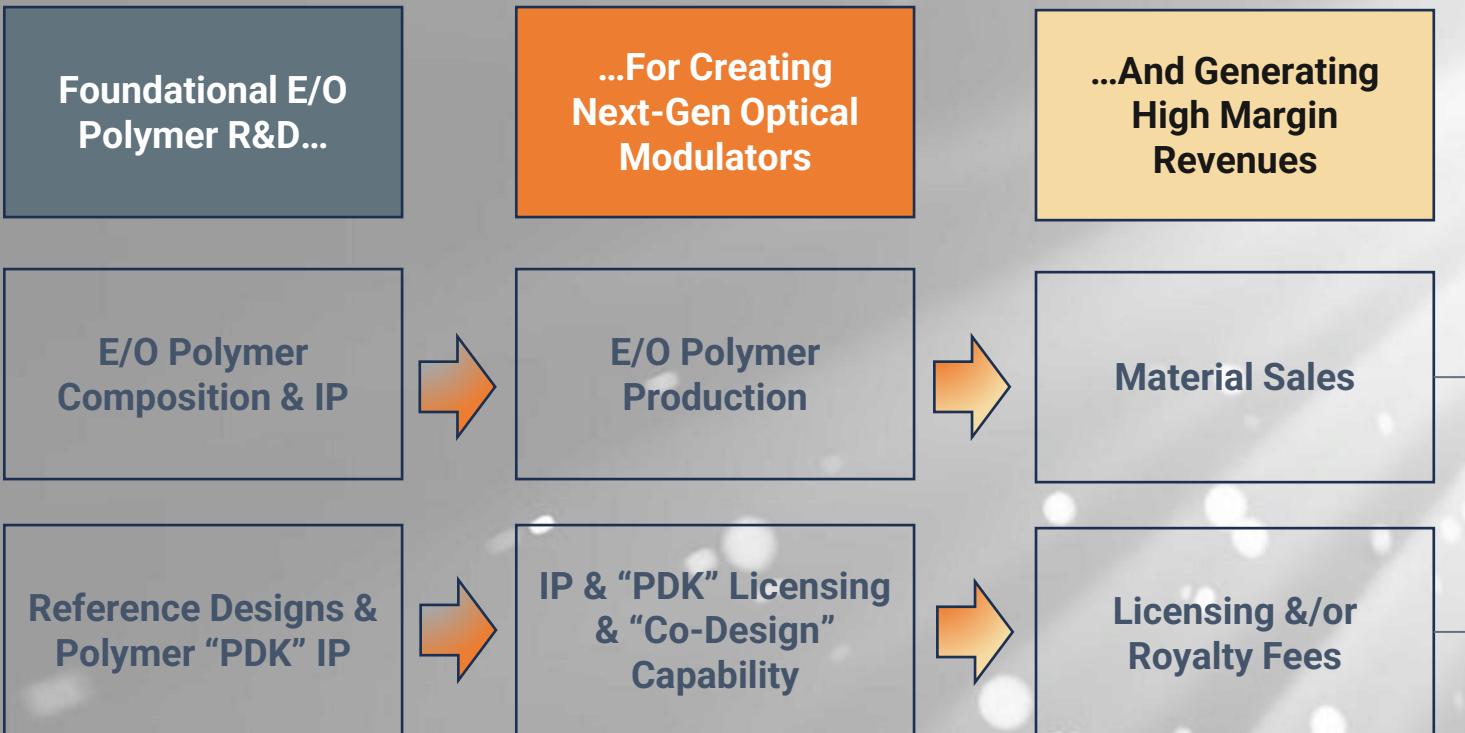
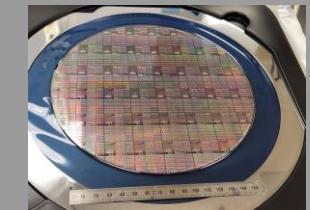
"We look forward to collaborating with QPICs on photonic-based quantum solutions to advance this exciting new market," said Yves LeMaire, CEO and President of Lightwave Logic. "Our shared cultures of disruptive innovation, along with the close proximity of our respective facilities, will allow us to collaborate efficiently to address the growing need of quantum computing and sensing customers for scalable, cost-effective, PIC-based solutions."

"QPICs goal is to establish the nation's leading quantum technology fab in Boulder as part of the US Department of Commerce's Tech Hub initiative that supports Colorado's Elevate Quantum eco-system," said Dr. Chris Myatt, QPICs Founder and CEO. "The ability to use silicon fab compatible materials from Lightwave Logic to develop quantum circuits is a critical step for us to further advance this vision. We're excited to partner with Lightwave Logic and look forward to our future collaboration."



Our Business Model

Material + IP/Royalty Licensing Company



60%+

Gross Margin at Scale

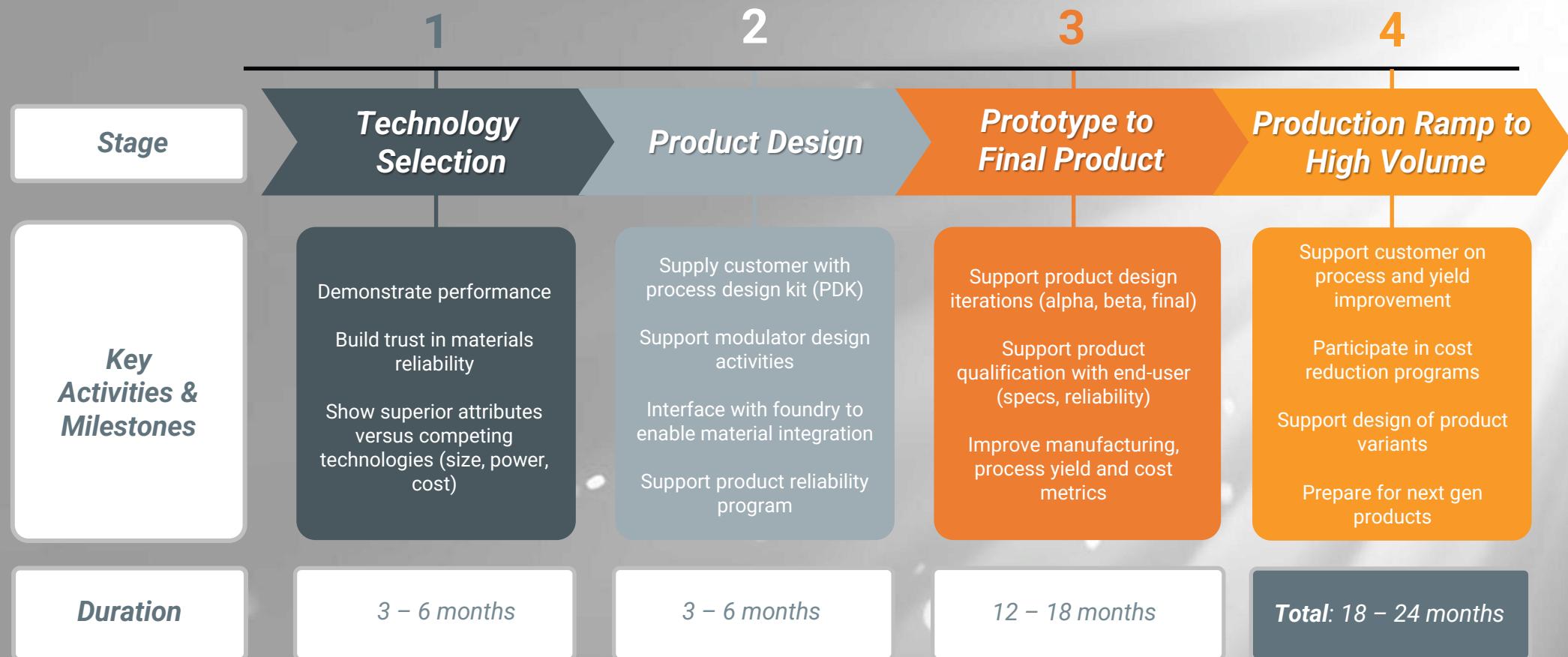


LIGHTWAVELOGIC®



LIGHTWAVE LOGIC®

Design Win Cycle



Three customers currently in Stage 3; >15 in Stages 1 & 2

Key Takeaways

Strong platform + favorable market dynamics to enable utilization of electro-optic polymers for high speed, low power AI and data center applications.



Unprecedented Accelerating Demand

- TAM of \$24B and SAM of \$1-2.5B by 2028 are growing quickly
- Driven by CapEx to address AI, quantum, datacomm & space comm requirements



Innovative EO Polymer Technology

- Disruptive technology enabler for future speed upgrades in data bandwidth
- Relieves key bottlenecks in AI infrastructure



Strong Patent Portfolio

- Protected by broad IP portfolio with over 80 patents
- Numerous patents pending



Deeply Experienced Leadership

- Management, Board of Directors, Advisory Board have 200+ years conceiving and launching products



Robust Balance Sheet

- Critical for execution
- \$35M cash position provides significant optionality and execution runway (as of 9/30/25)
- Raised \$35M in December 2025 through Public Offering



L I G H T W A V E L O G I C®

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